

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ084N08NS5	**Issued**	27. April 2022
MA#	MA005730656		
Package	PG-TSDSON-8-36	**Weight***	35.60 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.552	1.55	1.55	15510	15510
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		412	
	non noble metal	iron	7439-89-6	0.293	0.82		8234	
	non noble metal	copper	7440-50-8	11.903	33.43	34.30	334337	343086
wire	noble metal	gold	7440-57-5	0.029	0.08	0.08	805	805
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		976	
	plastics	epoxy resin	-	1.598	4.49		44890	
	inorganic material	silicondioxide	60676-86-0	15.739	44.23	48.82	442071	487937
leadfinish	non noble metal	tin	7440-31-5	0.420	1.18	1.18	11810	11810
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	88	88
solder	noble metal	silver	7440-22-4	0.020	0.06		574	
	non noble metal	tin	7440-31-5	0.041	0.11		1149	
	non noble metal	lead	7439-92-1	0.757	2.12	2.29	21250	22973
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		141	
	non noble metal	iron	7439-89-6	0.101	0.28		2827	
	non noble metal	copper	7440-50-8	4.087	11.48	11.77	114788	117791
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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